**Product / Process Change Notice**

**Parts Affected:**

Chip process CPS041, Silicon Controlled Rectifiers.

**Part Numbers Affected:**

|  |  |
| --- | --- |
| CS92B | 2N5060 |
| CS92D | 2N5061 |
| CS92M | 2N5062 |
| CS92N | 2N5063 |
|  | 2N5064 |
|  |  |

**Extent of Change:**

The CPS041 wafer process has been discontinued and replaced with the CPS043 wafer process. There have been slight changes in die size that do not negatively impact electrical performance.

**Reason for Change:**

An alternate wafer foundry was approved for this process in order to enhance capacity and mitigate any future disruption to product supply.

**Effect of Change:**

This change does not affect the electrical characteristics of the product. Updated curves to be provided upon completion of qualification.

**Qualification:**

Standard evaluation and qualification testing is in-process.

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

**Figures:**

 **Figure 1: CPS041 Chip Geometry (Discontinued) Figure 2:CPS043 Chip Geometry (Replacement)**





Wafer Diameter: 4 inch

Die Size: 43.3 x 43.3 mils

Die Thickness: 8.3 mils

Bond Pad Size (Cathode): 19.7x 9.5 mils

Bond Pad Size (Gate): 7.9 x 7.9 mils

Topside Metal: Al (30,000Å)

Backside Metal: Al/Mo/Ni/Ag

(20,000Å/5,000Å/5,000Å/2,000Å)

Wafer Diameter: 4 inch

Die Size: 41 x 41 mils

Die Thickness: 8.7 mils

Bond Pad Size (Cathode): 18 x 8 mils

Bond Pad Size (Gate): 7.1 x 7.1 mils

Topside Metal: Al (45,000Å)

Backside Metal: Al/Mo/Ni/Ag

(20,000Å/5,000Å/5,000Å/2,000Å)

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |